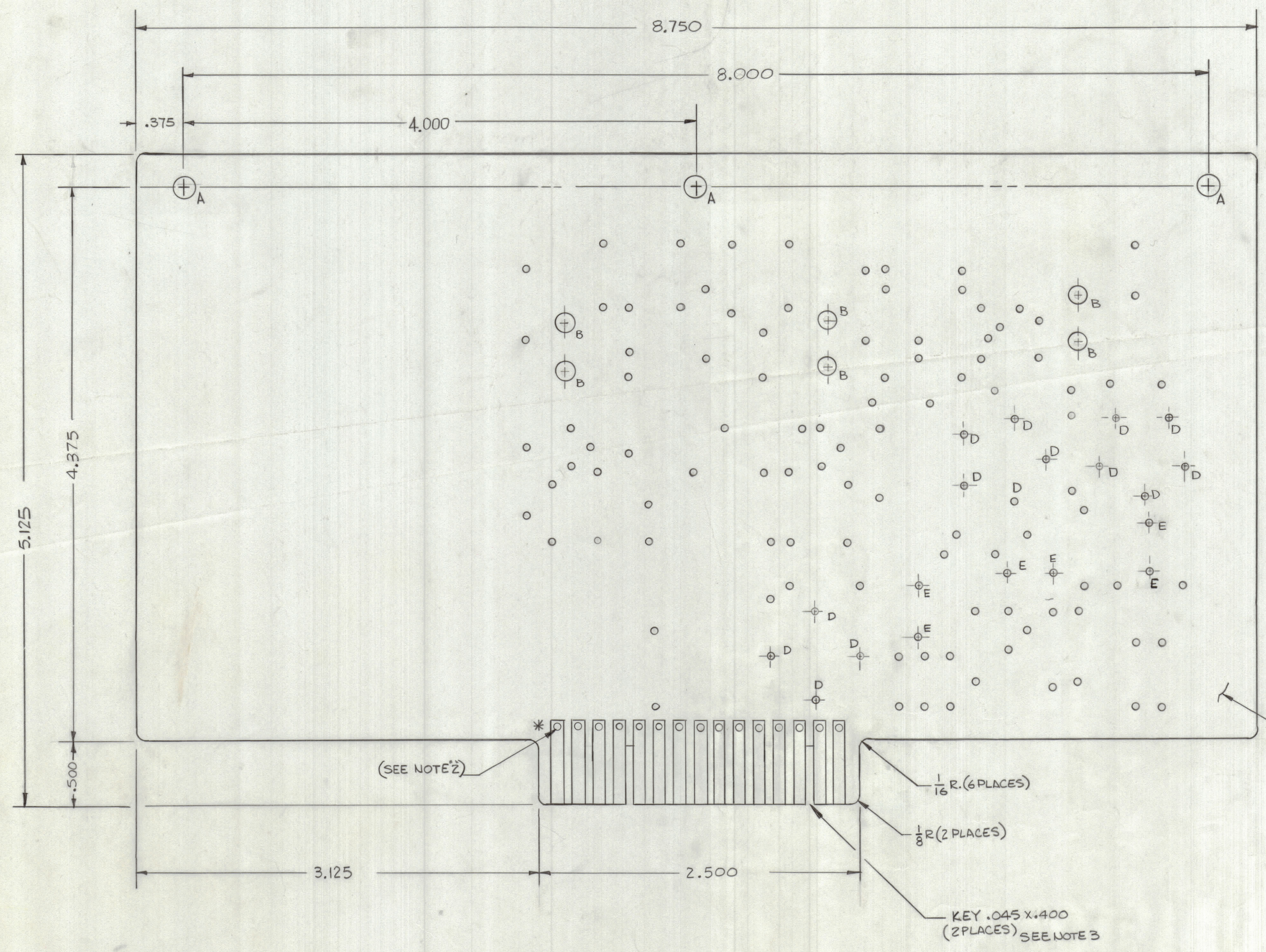


REVISIONS						
ZONE	SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD
Ø		ORIGINAL RELEASE FOR PRODUCTION	6-9-65	1		



HOLE	DESCRIPTION	REQ
A	11/64 DIA	3
B	.166 DIA	6
D	.050 DIA	14
E	.096 DIA	6
	UNMARKED .040 DIA	117

- FABRICATION NOTES
1. MATERIAL THICKNESS .062 ± .0075 AS PER 3.2 13.2.2
 2. .040 DIA. PLATED THRU HOLES, TO BE LOCATED IN THE CENTER OF EACH FINGER CONTACT .050 AWAY FROM THE MAIN BODY OF BOARD.
 3. THE PRINTED CIRCUIT BOARDS SHALL BE KEYED WITH SLOTS .050-.070 WIDE & .400 HIGH LOCATED BETWEEN FINGER CONTACTS 4 & 5 13, 14 AS VIEWED FROM COMPONENT SIDE OF BOARD.
 4. EDGE BOARD CONNECTOR (FINGER) SHALL BE GOLD PLATED 10.1 CONDUCTIVE PATTERN SHALL BE SOLDER COATED (PP13.3 & PP13.3.1)
 5. HOLES TO BE PLATED THRU AS PER (PP11.4)
 6. KEY SLOTS TO BE DEBURRED.
 7. FOR SPARE PARTS USE ON MODEL LFSB-1 SERIAL NO. 16336 THRU 16361, BOARD THICKNESS MUST BE .093 (3/32)

COMPONENT SIDE

PC180

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
LIST OF MATERIAL				
MATERIAL		THE TECHNICAL MATERIEL CORP.		
(SEE NOTE)		MAMARONECK, NEW YORK		
FINISH		TITLE		
		PRINTED CIRCUIT BD		
		1-8 MC GEN MODULE		
UNLESS OTHERWISE SPECIFIED		DRAWN	DATE	FINAL APPROVAL
DIMENSIONS ARE IN INCHES AND INCLUDE		CHECKED	DATE	DATE
CHEMICALLY APPLIED OR PLATED FINISHES		ELECT. DES.	DATE	
		MECH. DES.	DATE	
THE CONTENTS OF THIS DRAWING ARE THE EXCLUSIVE PROPERTY		DECIMALS		
OF THE TECHNICAL MATERIEL CORP. ITS UNAUTHORIZED USE OR		.X ± .05		
REPRODUCTION IN WHOLE OR IN PART IS STRICTLY FORBIDDEN.		.XX ± .01		
		.XXX ± .005		
		FRACTIONS		
		± 1/64		
		ANGLES		
		± 0° 30'		
		SHEET 2 OF 2		

NOTES